

IN THE SPECIFICATION:

Replace the paragraph starting at line 1 of page 13 with the following rewritten paragraph:

E1 A plurality of electronic components having conductive connecting members are surface-mounted to a target surface of a circuit board by specifying terminal-forming areas that are each no greater than the corresponding one of the electronic components and each include at least one terminal part such that at least one of these terminal-forming areas includes a plurality of terminal parts directly and that each pair of the terminal parts within any one of the terminal-forming areas is closer to each other than any pair of the terminal parts in different ones of the terminal-forming areas. An anisotropic conductive layer is formed on this target surface so as to span these terminal-forming areas, and the plurality of electronic components are placed on this anisotropic conductive layer individually above the plurality of terminal-forming areas. As the layer is heated, these electronic components are pressed against the layer such that the conductive connecting members of the electronic components become attached to and electrically conductive with corresponding ones of the terminal parts on the circuit board. The anisotropic conductive layer remains electrically insulative elsewhere.

IN THE CLAIMS:

Amend claim 1 as follows:

1. (Five times amended) A method of surface-mounting a plurality of electronic components having conductive connecting members, said method comprising the steps of:

providing a target surface having a plurality of specified terminal-forming areas thereon, each of said specified terminal-forming areas being no greater than corresponding one of said electronic components and including at least one terminal part therein, at least